

Vacuum Coating System



UNIVEX 250

Smart Choice for Seamless Coating Applications

In the dynamic world of scientific exploration and technological advancement, the UNIVEX 250 is your gateway to seamless coating processes, designed for universities, scientific labs, technical high schools, and industrial R&D facilities worldwide.

With the UNIVEX 250, you benefit from a cost-effective solution without compromising on quality or performance, meeting your diverse coating needs from contact metallization to contrast imaging for microscopy or thin film applications.

- Frame with heavy-duty castors accommodates the vacuum chamber with pump system and the control unit with electrical process components as well as color monitor
- Cubic stainless-steel chamber, with hinged aluminum front door for easy access to the process equipment
- Easily removable stainless-steel liners for protection of inner chamber walls and front door against deposition
- Powerful high-vacuum pumping system



Features and benefits

- Cost-effective starter system: begin your coating journey without breaking the bank.
- **Simple operation:** intuitive controls for hassle-free operation for users of all levels.
- Convenient access: easy access to your system for maintenance and operation.
- Modular extendibility: scale your system according to evolving needs with our modular design.
- **Mobile system:** take your capabilities wherever you go, enabling flexibility and convenience.
- Vacuum chamber: stainless steel chamber with hinged aluminium front door and inspection window.
- **Substrate coatings:** precisely controlled coatings for single substrates in R&D, and prototyping.
- Maximum substrate: accommodates up to Ø 200 mm.

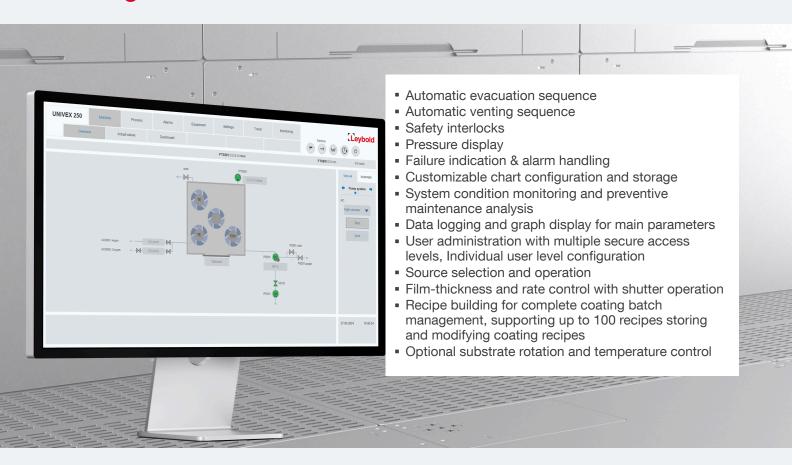
Technical Data

Technical data	UNIVEX 250	
Overall dimensions	approx. 1,400 mm x 950 mm x 1,800 mm (W x D x H)	
Weight	Weight approx. 500 – 600 kg	
Chamber Inner dimensions	270 mm x 370 mm x 400 mm (W x D x H)	
Max. Substrate size Ø 200 mm		

System information & requirements

Power Supply	System Base Pressure	Cooling Water Supply	Compressed Air Supply
400 V, 3-phase/N/PE, 50-60 Hz	≤1 E-06 mbar (vented with dry nitrogen)	8-15 l/min at 4 bar inlet at 18–25°C (Outlet-pressure less)	4–7 bar

Intelligent functions



UNIVEX software features

Comfortable system operation via large display using UNIVEX.exe software allows



Fully automated batches



Data logging and graph display for main parameters



Remote control



Manual mode



System condition monitoring and preventive maintenance analysis



User administration with multiple secure access levels, Individual user level configuration



Recipe processing allows programming, store and modifying recipes with adjustable parameters for different single or multiple layers

Standard configurations

Designed to start your operations with high quality and performance.

Choose from four pre-configured standard models, each offering attractive pricing and delivery times.

	UNIVEX 250 for				
	Thermal Evaporation	Electron beam evaporation	DC-Sputtering	RF-Sputtering	
Pump system	_				
High vacuum pump	TURBOVAC 450 i	TURBOVAC 450 i	TURBOVAC 450 i	TURBOVAC 450 i	
Backing Pump	TRIVAC D8T	TRIVAC D8T	TRIVAC D8T	TRIVAC D8T	
Pressure regulation			Butterfly-Valve for pressure regulation, DN 160 ISO-F	Butterfly-Valve for pressure regulation, DN 160 ISO-F	
Process equipment for	or				
Thermal evaporation	1 x Single thermal evaporator 1 x Power supply (2 kVA)				
Electron beam evaporation		1 x Multi-pocket electron beam evaporator (4 x 4 cm³) 1 x High voltage power supply (3kW)			
Sputtering			1 x Ø 2" Magnetron, confocal, Sputter Up 1 x DC power supply (500W)	1 x Ø 2" Magnetron, confocal, Sputter Up 1 x RF power supply (300W)	
Film-Thickness measurement	1 x Controller with 1 x quartz crystal sensor head	1 x Controller with 1 x quartz crystal sensor head			
Substrate					
Max. size	Ø 4"	Ø 4"	Ø 4"	Ø 4"	
Rotation	0-20 rpm	0-20 rpm	0-20 rpm	0-20 rpm	
Gas inlet			1 x MFC for Ar	1 x MFC for Ar	
System control	PLC with monitor	PLC with monitor	PLC with monitor	PLC with monitor	
	UNIVEX 250 for				
Order data	Thermal evaporation	Electron beam evaporation	DC-Sputtering	RF-Sputtering	
Part no.	505600V001	505601V001	505602V001	505603V001	

Customized solutions

100% customized to customer's needs based on well proven modules

Create your ideal system:				
Pumping System	 Various options for backing pumps HV-Gate valve and Bypass Butterfly-Valve for pressure regulation 			
Process equipment	 Thermal evaporation Co-Evaporation using single evaporators Electron beam evaporation Combination with thermal evaporation RF & DC sputtering Co-Sputtering Combination with thermal evaporation 			
Substrate treatment Film-Thickness measurement and control	 Rotation Heating Watercooling Substrate shutter Additional quartz crystal sensors 			
Process Gas inlet	For sputtering and/or reactive processes			







and much more...



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